

# **HRW0203B**

# Silicon Schottky Barrier Diode for Rectifying

REJ03G0155-0100Z

(Previous: ADE-208-1475)

Rev.1.00 Jan.06.2004

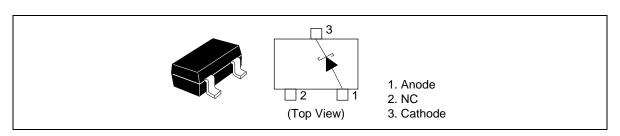
#### **Features**

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK package is suitable for high density surface mounting and high speed assembly.

### **Ordering Information**

Type No.	Laser Mark	Package Code	
HRW0203B	S21	MPAK	

#### **Pin Arrangement**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V <sub>RRM</sub> *1	30	V	
Average rectified current	l <sub>o</sub> * 1	200	mA	
Non-Repetitive peak forward surge current	I <sub>FSM</sub> * <sup>2</sup>	3	Α	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Notes: 1. See from Fig.1 to Fig.5, with polyimide board

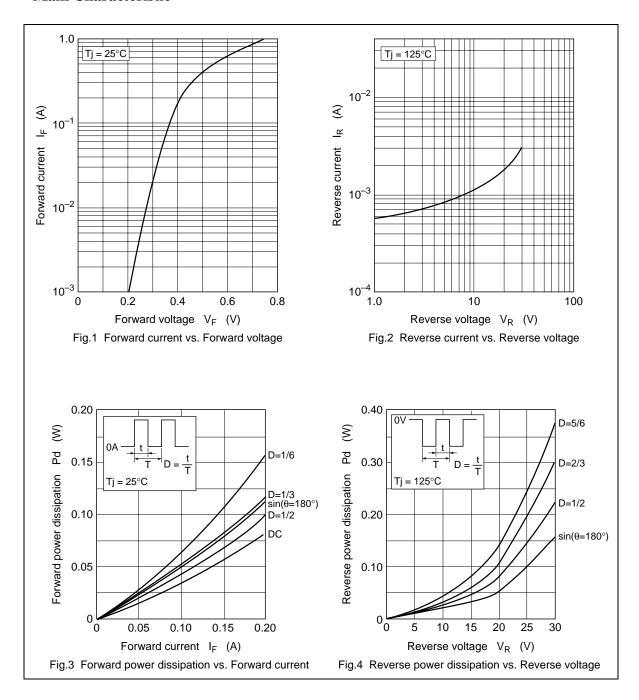
2. 50 Hz sine wave 1 pulse

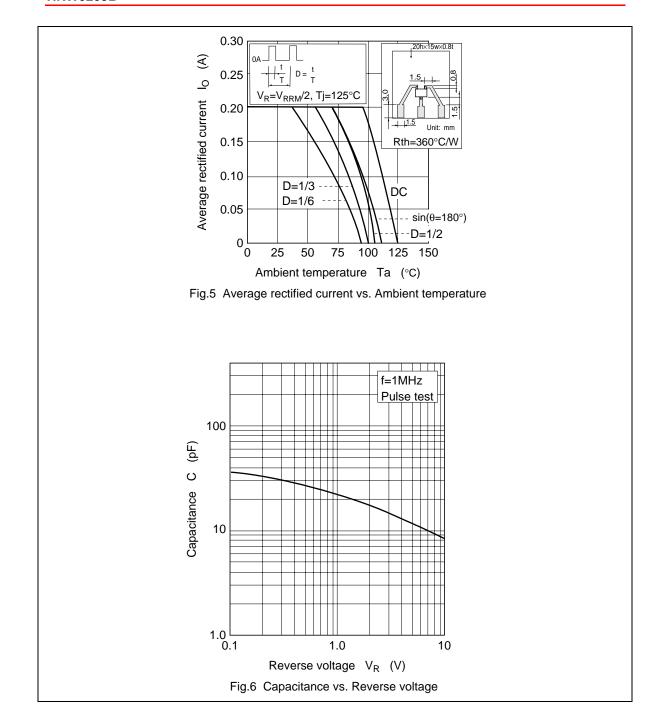
#### **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

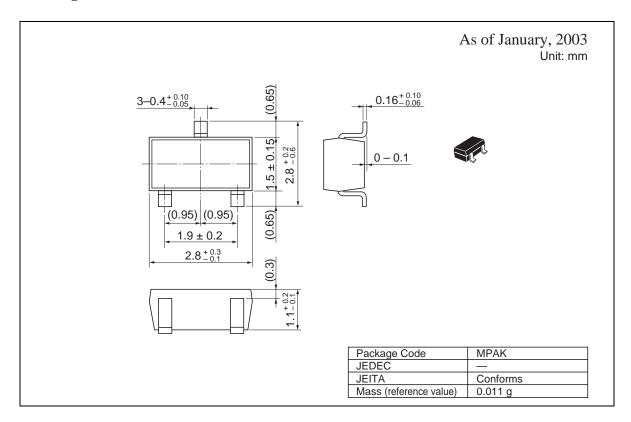
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F</sub>	_	_	0.5	V	I <sub>F</sub> = 200 mA
Reverse current	I <sub>R</sub>	_	_	50	μΑ	V <sub>R</sub> = 30 V
Capacitance	С	_	40	_	pF	V <sub>R</sub> = 0 V, f = 1 MHz

#### **Main Characteristic**





# **Package Dimensions**



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Renesas Technology Europe Limited.

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom Tel: <44> (1628) 585 100, Fax: <44> (1628) 585 900

Renesas Technology Europe GmbH Dornacher Str. 3, D-85622 Feldkirchen, Germany Tel: <49> (89) 380 70 0, Fax: <49> (89) 929 30 11

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Renesas Technology Singapore Pte. Ltd.
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632 Tel: <65> 6213-0200, Fax: <65> 6278-8001